

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC014N04LSI	**Issued**	02. June 2021
MA#	MA001073322		
Package	PG-TDSON-8-17	**Weight***	118.53 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.009	0.85	0.85	8516	8516
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		96	
	non noble metal	iron	7439-89-6	0.038	0.03		319	
	non noble metal	copper	7440-50-8	37.762	31.88	31.92	318589	319004
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	376	376
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		732	
	plastics	epoxy resin	-	6.156	5.19		51940	
	inorganic material	silicondioxide	60676-86-0	37.112	31.31	36.57	313105	365777
leadfinish	non noble metal	tin	7440-31-5	1.452	1.22	1.22	12247	12247
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1397	1397
solder	non noble metal	tin	7440-31-5	0.029	0.02		245	
	noble metal	silver	7440-22-4	0.036	0.03		306	
	non noble metal	lead	7439-92-1	1.387	1.17	1.22	11701	12252
heat sink clip	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	zinc	7440-66-6	0.026	0.02		223	
	non noble metal	iron	7439-89-6	0.529	0.45		4464	
	non noble metal	copper	7440-50-8	21.482	18.12	18.60	181242	185985
heatspreader	inorganic material	phosphorus	7723-14-0	0.003			28	
	non noble metal	zinc	7440-66-6	0.013	0.01		113	
	non noble metal	iron	7439-89-6	0.269	0.23		2267	
	non noble metal	copper	7440-50-8	10.909	9.20	9.44	92038	94446
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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